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DESCRIPTION

BACKGROUND OF THE INVENTION

[0001] This invention relates to cards, such as credit cards, plastic cards for ID, financial transactions and other uses, having improved durability and appearance and to apparatus and methods for making such cards. Included in the manufacture is the application of a clear laminate during the manufacture of the cards.

[0002] The use of plastic credit cards is widespread. A problem with known plastic cards is that they warp and wear out from repeated use (e.g., within 3-5 years and after 4000 uses - swipes of the magnetic stripe) and the markings become faint or scratched. It has therefore been an aim of the industry to make cards which are sturdier and whose markings do not fade with repeated use. That is, it is desirable to have plastic cards that can last many (e.g., 5-10) years and which can be subjected to a very large number (e.g., 10,000) of uses; especially magnetic stripe use.

[0003] In the past, attempts were made to make the credit card surface harder. For example, cards were made with an ultra violet cured coating. However, all such harder cards were prone to develop cracks due to stress over time. This made these cards undesirable for their intended use.

[0004] In EP 0 368 570 A2, an optical card structure is disclosed which is intended for the application of laser light to record data rather than for personalization. The light intensity required is lower than that required for personalization and so there is no requirement for a buffer layer to prevent damage to the hard coat layer. JP 2002 260290 A discloses the production of a card by the building up of successive layers, with a hard coat being applied to one side of a transparent substrate and a recording layer being applied on the opposite surface. The only buffer layer present is disposed on the opposite side of the recording layer from the hard coat layer, and so is not serving to protect the hard coat layer.

[0005] It is therefore desirable to manufacture a hardy, scratch resistant plastic card which is not prone to develop cracks and to make such cards easy and economical to manufacture.

[0006] It is also desirable to manufacture a metal card which is scratch resistant and is also more durable.

SUMMARY OF THE INVENTION

[0007] The method of the invention is set out in the claims.

[0008] Cards embodying the invention include a hard coat layer formed on top and/or on the bottom of the card. The hard coat layer may be formed of nano-particles, such as silicate nanoparticles, zinc oxide nanoparticles, silicon dioxide crystalline nano-particles, or any other suitable nano-particles with a suitable carrier such as a solvent of water based acrylates, vinyls, urethane or the like. The hard coat can be applied by coating techniques such as gravure, reverse roll, direct roll, or slot coating.

[0009] The hard coat layer may be applied to a card, or to a subassembly used in forming a card, by means of a special carrier layer. The special carrier enables a release layer and a hard coat layer to be attached to the special carrier layer to form a subassembly which can then be attached and transferred to another subassembly to form an intermediate assembly from which the carrier and release layers can be removed, leaving the hard coat layer as the top and/or bottom layer of the card.

[0010] Cards embodying the invention include a core subassembly whose elements define the functionality of the card and a hard coat subassembly attached to the top and/or bottom sides of the core subassembly. The core subassembly may be formed solely of plastic solely of plastic layers or of different combinations of plastic and metal layers or essentially purely metal layers. The core subassembly may also include;

1. (a) a semiconductor chip containing selected electronic circuits and an antenna coupled to the chip for enabling contactless radio frequency (RF) communication with an external reading device; and/or
2. (b) a semiconductor chip with contacts to an external surface of the card to enable direct "contact" communication with an external reading device.

[0011] Cards embodying the invention include an energy absorbing buffer layer formed between a hard coat layer and a layer intended to be treated (e.g., personalized) with a laser.

BRIEF DESCRIPTION OF THE DRAWINGS

[0012] In the accompanying drawings, which are not drawn to scale, like reference characters denote like components; and

Fig. 1A is a highly simplified cross sectional diagram of a "core" plastic card sub assembly (subassembly A) which may be used in practicing the invention;

Fig. 1A1 is an isometric diagram of a core, contactless, plastic card subassembly showing various layers of the subassembly including a layer carrying a chip and one carrying an antenna;

Fig. 1A2 is a highly simplified cross sectional diagram of a "core contact" plastic card sub

assembly (subassembly A) which may be used in practicing the invention;

Fig. 1B is a highly simplified cross sectional diagram of a hard coat layer sub assembly (subassembly B) intended to be combined with assorted core subassemblies to form durable cards embodying the invention;

Fig. 1C is a highly simplified cross sectional diagram of a core plastic card sub assembly (subassembly A) combined with a hard coat layer sub assembly (subassembly B) in accordance with the invention;

Fig. 1D is a highly simplified cross sectional diagram of a resultant durable plastic card with a hard coat layer in accordance with the invention;

Fig. 2 is a highly simplified cross sectional diagram of a core plastic card sub assembly (subassembly A) combined with hard coat subassemblies located on the top and bottom sides of the card;

Fig. 2A is a highly simplified cross sectional diagram of a resultant durable plastic card with hard coat layers on the top and bottom side of the card in accordance with the invention;

Fig. 3A is a highly simplified cross sectional diagram of prior art platens used in the manufacture of cards;

Fig. 3B is a highly simplified cross sectional diagram of platens embodying an aspect of the invention used in the manufacture of cards;

Fig. 4A is a highly simplified cross sectional diagram of a metal card assembly for manufacturing a durable metal card in accordance with the invention;

Fig. 4A1 is an isometric diagram of a core, contactless, metal-plastic card subassembly showing various layers of the subassembly including a layer carrying a semiconductor chip and one carrying an antenna;

Fig. 4A2 is a cross sectional diagram of part of a core metal-plastic card subassembly which includes a module and antennas so the subassembly can be used to form a contact card and/or a contactless card;

Fig. 4B is a highly simplified cross sectional diagram of a resultant durable metal card formed with a hard coat layer on the top and bottom sides of the card in accordance with the invention;

Fig. 5A is a highly simplified cross sectional diagram of a "brushed" metal card assembly for manufacturing a durable metal card in accordance with the invention;

Fig. 5B is a is a highly simplified cross sectional diagram of a durable "brushed" metal card formed with a hard coat layer on the top and bottom sides of the card in accordance with the invention;

Fig. 6A is a highly simplified cross sectional diagram of an "embedded" metal card assembly for manufacturing a durable metal card in accordance with the invention;

Fig. 6B is a highly simplified cross sectional diagram of a "hybrid" metal card assembly for manufacturing a durable metal card in accordance with the invention;

Fig. 7 is a flow chart diagram showing various processing steps in forming cards embodying the invention;

Fig. 8 is a diagram illustrating the use of an energy absorbing buffer layer between a metal layer and a hard coat layer when the metal layer is subjected to a heat generating laser beam; and

Fig. 9 is a diagram illustrating the use of an energy absorbing buffer layer between a carbon containing PVC layer and a hard coat layer when the carbon containing layer is subjected to a heat generating laser beam.

DETAILED DESCRIPTION OF THE INVENTION

[0013] As shown in the various figures, cards embodying the invention include a "core" subassembly (subassembly A or A1, C, D, E, or F, or a subassembly as shown in Figs. 1A2 and 4A2) which defines the functionality of the card to which is attached a hard coat subassembly (subassembly B); where the hard coat subassembly can be attached to the bottom and top sides of the core subassembly or to only one side of the core subassembly.

[0014] The "core" subassembly may comprise: (a) a number of plastic layers attached together as shown in Fig. 1A; or (b) a number of plastic layers with a chip and antennas (a contactless "smart" card) carried on one or more of the layers as shown in Fig. 1A1; or (c) a number of plastic layers with a chip and antennas and a contact (a contact or contactless "smart" card) as shown in Fig. 1A2; or (d) a number of metal-plastic layers, forming a hybrid card, as shown in Figs. 4A and 4B; or (e) a number of metal-plastic layers, forming a hybrid card, with a chip and antennas formed on or within some of the plastic layers (a contactless "smart" card) as shown in Fig. 4A1; or (f) a number of metal-plastic layers, forming a hybrid card, with a chip and antennas formed on, or within, some of the plastic layers and with contacts extending to a surface of the card as shown in Fig. 4A2; or (g) a number of metal-plastic layers, as shown as subassembly D in Figs. 5A, 5B, as subassembly E in Fig. 6A, and subassembly F in Fig. 6B. The core subassembly could also be formed of a relatively thick metal layer.

[0015] An overview of the general processing steps performed in the manufacture of cards embodying the invention is shown in Fig. 7. As indicated in step 701 of Fig. 7, forming a "core" subassembly is one step in the process of making cards in accordance with the invention. As indicated in step 703 of Fig. 7, another step in the process is forming a hard coat subassembly B having a structure of the type shown in Fig. 1B.

[0016] The next step as shown in step 705 of Fig. 7, is forming a "sandwich" comprising the step of attaching a hard coat subassembly to the top and bottom sides of a core subassembly (as shown, for example, in Fig. 2) or to only one side of the core subassembly (as shown, for example, in Fig. 1C).

[0017] The next step as shown in step 707 of Fig. 7 is to laminate the sandwich to form a reliable and firm card. Of significance in the manufacture of cards embodying the invention is the use of a silicone rubber plate designed to ensure that air bubbles are removed.

[0018] The next step shown in step 709 of Fig. 7 is the removal of the special carrier and release layer leaving the exposed hard coat layer(s). After the removal of the carrier and release layers a resultant card is produced as per step 711.

[0019] Also of significance in the manufacture of cards embodying the invention is a lasering step to personalize/write on a metal core layer or on a PVC core layer of the card. The lasering step can be selectively performed at any of several points during the process of making the cards (e.g., after step 701, or 705 or 707 or 709 or 711).

[0020] Some of the detailed steps in the manufacture of a durable card as shown in Figs 1A, 1B, 1C and 1D include the following:

1. 1- As shown in Fig. 1A, information (103a, 103b) may be printed in, or on, a core polyvinyl chloride (PVC) layer 101. A clear plastic layer 102a positioned above layer 101 and another clear plastic layer 102b positioned below layer 101 are laminated together with layer 101 using standard processing equipment. A magnetic stripe layer 120 may be laminated with layers 101, 102a and 102b at the same time or subsequently thereto. The laminated assembly of layers 102a, 101, 102b and 120 is identified as subassembly A, which represents a core subassembly suitable for practicing the invention..
2. 2- As shown in Fig. 1A1 subassembly A may be modified to include a layer 100 carrying a booster antenna 14 and a layer 100a carrying a chip module 12 and a chip antenna 13. Layers 100 and 100a may be two separate layers or there may be one plastic layer carrying the chip module and the antennas. The chip module, also referred to as a semiconductor chip or an integrated circuit (IC) includes electronic circuitry which is connected to antenna 13 inductively coupled to antenna 14 to enable the module 12 to communicate via contactless radio frequency (RF) with an external card reading device (not shown). For ease of reference a subassembly A modified to include a chip and antenna(s) may be identified as a subassembly A1, which represents another "core" subassembly suitable for practicing the invention.
3. 3- Note that, as shown in Fig. 1A2, the subassembly A may also be modified to include contacts extending from the module 12 to contact points 121, 123 along an external surface of a card. These contacts (121, 123) enable an external card reader (not shown) to directly contact and interact with the chip module 12. The modified subassembly also represents another core subassembly suitable for practicing the invention.
4. 4- As shown in Figs. 1B and 1C, a hard coat sub-assembly B is formed to be combined

with a core subassembly (A or A1) to form a durable card embodying the invention. Subassembly B is referred to herein as a hard coat subassembly. As shown in Fig. 1B, subassembly B includes a special carrier layer 104 on which is positioned a release layer 106 on which is formed a hard coat layer 108 on which is formed a primer layer 110 to which is attached an adhesive layer 112. The layers forming subassembly B can come in rolls or sheets (films) which are stacked on top of each other in the prescribed order and then processed (combined) in the following manner. Heat and pressure are applied to the layers forming subassembly B fusing the stack of sheets (or rolls) together. The entire lamination process may occur in one or two steps depending on the equipment available. That is subassemblies A and B may be laminated separately and then combined. Alternatively, all the layers of subassemblies A and B can be stacked together as shown in Figs. 1C and 2 and then laminated at the same time.

5. 5- The layers of subassembly B have significant properties, as discussed below:

a- special carrier layer 104, the carrier material is typically polyester, and is typically 0.00075 inches thick. The carrier layer is formed so that a release layer and a hard coat layer (also primer and adhesive) can be formed thereon and such that the carrier and release layer can be removed, leaving the hard coat layer (108a, 108b) as the top (or bottom) layer of the card. The carrier layer 104 is important due to being specially designed to be compatible with the lamination process and to impart a special finish to the hard coat on the card.

b- The release layer 106 material is, by way of example, polyethylene wax and is approximately 0.00025 inches thick.

c- hard coat layer 108- The hard coat layer may be formed of nano-particles, such as silicate nanoparticles, zinc oxide nanoparticles, silicon dioxide crystalline nanoparticles, or any other suitable nano-particles with a suitable carrier such as a solvent of water based acrylates, vinyls, urethane or the like. The hard coat can be applied by coating techniques such as gravure, reverse roll, direct roll, or slot coating. This avoids the size limitation of the vapor depositing equipment. The hard coat layer (108a, 108b) is scratch resistant and provides a very strong and long lasting surface. Bending and abrasion testing has shown that a plastic card with nano particle coating is superior to any of the e-coat jewelry finishes currently in use.

d- Primer layer 110 -- material is typically a plastic material such as polyvinyl dichloride, or any like material, and is typically 0.0003 inches thick. In accordance with the invention, the primer layer may be made to have many different colors by adding colorants, dyes or pigments, to the plastic primer layer. This is very significant since it enables the manufacture of colored durable cards much more cheaply than using other known techniques. The color is compounded with the primer and solvents prior to its application to the sheet or roll.

e- Adhesive layer 112 - may be, for example, polyvinyl acetate (PVA or PVAC), or any like adhesive or glue-like material. The adhesive layer must be such that it enables subassembly B to be bonded to a core subassembly (e.g., A or A1); the subassembly

whose components need to be protected.

6. 6- In accordance with one embodiment, the various layers of subassembly B are bonded together in a platen press at a predetermined temperature for a predetermined time at a given pressure (e.g., 300 degrees F at 200psia for 10 minutes).
7. 7- A core subassembly (e.g., A or A1) and a hard coat subassembly B are then combined together as shown in Fig. 1C or 2. The two subassemblies are then bonded (or laminated) together at a predetermined temperature for a predetermined time at a given pressure (e.g., 290 degrees F at 200 psia for 8 minutes).
8. 8- Alternatively, all the layers of subassemblies A and B could be bonded (sandwiched) together in a one step process if the adhesive system is designed for the application.
9. 9- The carrier layer 104 and the release layer 106 are then removed. Note that the hard coat subassembly with the carrier and release layer removed is identified as B1 in the drawings. In one embodiment, the plastic carrier layer 104 and release layer 106 are hand stripped by a lamination operator when breaking open the completed sandwiches (assemblies). Thus is formed a durable plastic card 10 of the type shown in Figs, 1D or 2A.
10. 10- A card 10 with the hard coat layer embodying the invention has the following properties: uniform surfaces which are scratch and abrasion resistant.
11. 11- Laserability - A laser (e.g., a YAG laser) can be used for personalization of the resulting outside card surface. Note that a lasering operation can be performed at many different points during the manufacturing process. The lasering may be performed at or on the surface of a card assembly or two layers within the core subassembly.

11 (a) - Laserability of cards which include only plastic layers -- As shown in Fig. 1C, selected layers (e.g., clear PVC laminate layers 102a, 102b or in an optional PVC overlay) of a core subassembly may be formed to contain laser reactive carbon particles 901. Carbon particles and fumed silica which can be laser reactive ingredients can be formed in the printed PVC or polymer layer or in the polymer overlay. Heat from the laser (e.g., 402) causes carbon particles in these layers to char and the surrounding area turns dark. With extra power from the layer in the same spot the silica steams off its water and causes the area to turn a light color. Thus the laser is capable of making both light and dark marks on the same plastic surface.

11(b) Laserability of cards which include a metal layer- This process shows good contrast and is very secure since the hard coat layer can be ablated down to the bare surface of the underlying metal. Note the hard coat layer is either ablated if it is in direct contact with the metal surface or unaffected (if adhesive and plastic layers are attached to the metal surface) depending upon how the print and background qualities of the card affect the laser beam reflection and absorption. Sometimes, with a powerful laser the surface of the metal may also be affected causing bright bare metal to remain.

[0021] The manufacture and processing of the proposed product will result in significant cost

savings over alternative methods due to a reduction of surface scratching. Card life in the field is also extended.

[0022] Figs. 2 and 2A illustrate that a hard coat layer can be formed on the top and on the bottom (both sides) of a card. Fig. 2 shows that a subassembly B, denoted as B(a), can be attached to the top side of a plastic core subassembly A and that a like subassembly B, denoted as B(b), can be attached to the bottom side of subassembly A with B(b) being the symmetrically disposed mirror image of 8(a) when folded about the center core. The entire sandwich of subassemblies B(a), A and B(b) can be laminated as discussed above. After lamination, the carrier and release layers 104a, 106a and 104b, 106b are removed. This results in a card of the type shown in Fig. 2A where hard coat layers 108a and 108b are formed as the topmost and bottommost layers of the card 10. The advantage of providing a hard coat layer 108b over the magnetic stripe layer 120 is that it would ensure that the magnetic stripe layer would not be worn out over the useful life of the card. The hard coat can be applied only over the magnetic stripe (leaving the signature panel open) or if a full layer of hard coat is applied, a laser signature can be used during personalization instead of a customer hand signed card signature.

[0023] The lamination step includes the use of separate heated and cooled platens to apply pressure at a predetermined temperature to the sandwich. Prior art platens as shown in Fig. 3A include the use of standard polished steel plates (301a, 301b) heated to the desired temperature to apply the desired pressure to selected layers. A problem with the prior art platens was that air bubbles within the layers could not escape. This caused defects on the laminated sheet. This problem is overcome by replacing the polished steel plates/pads with silicone rubber plates 311a, 311 b, as shown in Fig. 3B, to laminate cards embodying the invention. The use of a silicone rubber pads over the platens can provide a degree of flexibility in that it allows pressing of the hard coat into irregular areas of the sheet. This helps squeeze out air bubbles.

[0024] Furthermore, to overcome problems of manufacture and completely remove air entrapment a special vacuum lamination platen under heat and hydraulic pressure can be used with a high heat high pressure short cycle. The cards shown in the figures and formed in accordance with the invention benefit from the vacuum lamination process by completely removing air from the process.

[0025] The handling methods developed overcome lack of surface consistency by using special 30 durometer 032 to 062 thick silicone rubber, ----with or without vacuum. Lamination using silicone rubber platens also can overcome lack of surface consistency by providing a more even pressure which overcomes any inconsistency in material surface and thickness.

[0026] Relative to a metal core or hybrid card using the hard coat technique allows the user to achieve a holographic, multi-dimensional effect on stainless steel or similar metal substrate with a polished or mill finish by laser engraving an image removing a physical vapor deposition (PVD) or like pigmented coating. This may be achieved by creating a pseudo lenticular lens,

and changing the refractive index of the image on different layers. This may be further enhanced by creating a polarization pattern in the layers, creating a polarized light effect.

Metal cards -

[0027] In accordance with the invention, the hard coat subassemblies may be combined with core subassemblies which include metal layers to form metal-plastic or mostly metal cards which are highly scratch resistant and even more durable.

[0028] Figs. 4A and 5A are highly simplified cross sectional diagrams of a primarily metal card assembly for manufacturing a durable metal card in accordance with the invention. The metal layer 101 may include an optional adhesive film (103a, 103b) above it top and bottom surfaces. The optional adhesive films 103a, 103b are desirably used when the top and/or bottom surface of the metal layer 101 has been "brushed" as shown in Fig. 5A. The "brushing" may be accomplished by forming indentations in the surface of the metal layer done to give the metal layer and the resultant card a distinctive feature. The films 103a and 103b when applied to the brushed metal surfaces tend to smooth out the sharp edges and fill the depressions present on the brushed surfaces. This solves a problem when the ridges formed in the metal surfaces due to the "brushing" exceed the thickness of the hard coat layer and tend to wear through the hard coat layer. The core metal card subassembly (C in Fig. 4A, D in Fig. 5A) is shown to include a magnetic stripe and/or a hologram layer 120 on the bottom side of the metal layer. In Figs. 4A and 5A, the card assembly sandwich also includes a sub assembly Ba applied (sandwiched) on top of the optional adhesive film 103a and a subassembly Bb applied (sandwiched) below layer 120.

[0029] Note that the metal layer 101 may be stainless steel and have a "whitish" color. There is provided in subassemblies Ba and Bb a primer layer 110a, 110b which may be colored to give the card a desired color. Alternatively, the primer layer may be clear.

[0030] The sandwich assembly shown in Figs. 4A and 5A is subjected to a lamination process under predetermined pressure and temperature. Thereafter, the carrier and release layers are removed leaving a resultant card of the type shown in Figs. 4B or 5B. Thus, Figs. 4B and 5B are highly simplified cross sectional diagrams of a durable scratch resistant metal card formed with a hard coat layer on the top and bottom sides of the card in accordance with the invention. In Figs. 4A and 5A, the thickness of the metal layer 101 may be, but need not be, nearly the full thickness of the card.

[0031] Fig. 6A is similar to Figs. 4A and 5A except that an additional printed clear PVC layer 105a is applied above the metal layer 101 and an additional printed clear PVC layer 105b is applied below the metal layer 101. The PVC layers 105a, 105b, enable the metal layer 101 of Fig. 6A to be made thinner than the metal layer 101 of Figs. 4A and 5A. For example, the thickness of its metal layer may be 1/3 that of Figs. 4A and 5A, Fig. 6A may be referred to as a durable card with an "embedded" metal layer.

[0032] Fig. 6B is similar to Fig. 6A except that at least one of the PVC layers may be eliminated. The metal layer of Fig. 6B would be thicker than that of Fig. 6A but thinner than that of Figs. 4A or 5A. Fig. 6B may be referred to as a hybrid durable metal card. Note that the resultant cards formed from the assemblies shown in Figs. 6A and 6B have a hard coat layer on their top and on the bottom surfaces.

[0033] As already discussed a "core" subassembly as used herein refers to those layers of the card which define the functionality or function to be performed by the card. A "core" subassembly may be a subassembly such as defined as subassembly A, A1, or in Fig. 4A2, C, D, E or F).

[0034] Figs. 8 and 9 illustrate a solution to a problem which exists when a hard coat layer is used. It is noted that a problem exists when a hard coat layer is formed so as to be in direct contact with a metal layer or a plastic layer containing laser reactive (e.g., carbon) particles and the metal layer or a plastic layer undergoes a lasering operation. When the laser is applied to the metal layer or to the laser reactive plastic layer, a substantial amount of heat (energy) is generated. When this generated heat is applied to the hard coat layer, the hard coat layer is subjected to cracking and to being effectively destroyed.

[0035] In Fig. 8 the "cracking" problem is overcome by forming an energy absorbing layer (e.g., 808a, 808b) between a metal layer (e.g., 101) and associated hard coat layers (108a, 108b). The energy absorbing layer (e.g., 808a, 808b) may be of any suitable material to absorb or dissipate the energy generated to prevent cracking of the hard coat layer. In some embodiments a primer layer 110 in addition to an adhesive layer 112 formed between the hard coat layer and the metal layer were sufficient to protect the hard coat layer from the heat generated by the laser's action. An energy absorbing buffer layer may be comprised, for example, of an extruded polymer film, and can be composed of any of the polymeric films known in the art such as PET (Polyethylene Terephthalate), PETG (Polyethylene Terephthalate Glycol), or PVC (Polyvinyl Chloride).

[0036] In Fig. 9 the "cracking" problem is overcome by forming an energy absorbing layer (e.g., 908) between a laser reactive carbon containing plastic layer (e.g., 902) and associated hard coat layers (1080). The energy absorbing layer (e.g., 908) may be of any suitable material to absorb or dissipate the energy generated to prevent cracking of the hard coat layer, as discussed above for Fig. 8.

REFERENCES CITED IN THE DESCRIPTION

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Patent documents cited in the description

- EP0368570A2 [0004]
- JF2002260290A [0004]

PATENTKRAV

1. En metode til dannelsen af et transaktionskort med et lag (102a, 102b, 101), der kan behandles med laser til personalisering af kortet, og et lag med hård belægning (108, 108a) derover, med et energiabsorberende bufferlag (110a, 112a, 808a, 808b, 908) imellem laget, 5 der kan behandles med laser, og laget med hård belægning, metoden er kendetegnet ved trinnene:
- dannelse af en kerneunderenhed (A, A1, C, D, E, F) omfattende to eller flere lag inklusive laget, der kan behandles med laser, og omfattende en eller flere elementer (12, 13, 14, 120, 121, 123), som definerer kortets funktionalitet;
 - 10 nævnte første kerneunderenhed har et toplag og et bundlag;
 - dannelse af en underenhed med hård belægning (B) inklusive laget med hård belægning fastgjort til et slipbart lag monteret på et bærelag;
 - fastgørelse af underenheden med hård belægning (B) til kerneunderenhedens toplag, så laget med hård belægning er tættest på kerneunderenheden, og placering af bufferlaget 15 (110a, 112a, 808a, 808b, 908) imellem kerneunderenheden og laget med hård belægning, så der dannes en første kortenhed;
 - laminering af den første kortenhed under forudbestemt temperatur og tryk;
 - og fjernelse af sliplaget og bærelaget for at danne et resulterende kort.
- 20 2. En metode ifølge krav 1, hvor laget med hård belægning (108a, 108B) omfatter nanopartikler og en bærer for nanopartikler.
3. En metode ifølge krav 2, hvor nanopartiklerne er silikat-nanopartikler, zinkoxid-nanopartikler, silikonedioxidkrystallin-nanopartikler.
- 25 4. En metode ifølge krav 1, hvor underenheden med hård belægning omfatter et plastikprimerlag (110, 110a) nedenunder laget med hård belægning (108, 108a), og som omfatter trinnet tilføjelse af farvestoffer, farver eller pigmenter til plastikprimerlaget for at garantere fremstilling af farvede, holdbare kort.
- 30 5. En metode ifølge krav 1, hvor trinnet med laminering af første kortenhed omfatter trinnet med fjernelse af luftbobler og overflademangler.
6. En metode ifølge krav 1, hvor trinnet med laminering af første kortenhed omfatter

trinnet med brug af silikonegummivalser, hvis funktion er at tilføre tryk for at fjerne luftbobler fanget i lagene på den første kortenhed og for at gøre overfladen på den første kortenhed glat.

- 5 7. En metode ifølge krav 1, hvor en anden af nævnte underenhed med hård belægning er fastgjort til bundlaget på kerneunderenheden for at danne nævnte første enhed;
og hvor sliplaget og bærelaget på nævnte anden af nævnte anden underenhed fjernes for at danne et resulterende kort.
- 10 8. En metode ifølge krav 1, hvor den første kerneunderenhed omfatter et kerneplastiklag, klare PVC-lag med grafik på udvalgte af PVC-lagene og en magnetisk stribe.
9. En metode ifølge krav 1, hvor den første kerneunderenhed omfatter et metalkernelag.
- 15 10. En metode ifølge krav 8 eller 9, hvor kerneunderenheden også omfatter mindst en af følgende:
(a) et integreret kredsløb (12) og en antenne (13) for at muliggøre radiofrekvenskommunikation med en ekstern læseenhed;
og (b) et integreret kredsløb med kontaktpunkter (121, 123), som strækker sig på en
20 overflade af kortet for at muliggøre direkte kontakt og kommunikation imellem en ekstern enhed og det integrerede kredsløb.
11. En metode ifølge krav 1, derudover inklusive trinnet med selektiv laserbehandling af den første kerneunderenhed.
- 25 12. En metode ifølge krav 1, hvor laget, der kan behandles med laser, er et plastiklag (102a, 102b), som indeholder laserreaktive partikler (901) eller et metallag (101).
13. En metode ifølge krav 1, hvor bufferlaget er mindst en af følgende:
30 (a) et plastikmateriale såsom polyvinyldiklorid eller ethvert lignende materiale;
(b) et plastikmateriale, hvortil der er tilføjet farvestoffer, farver eller pigmenter;
(c) et plastikmateriale såsom polyvinylchlorid (PVC) eller polyvinylacetat (PVAC), amorf polyætylen-tereftalat (APET), polyætylen-tereftalat-glycol (PETG) eller ethvert lignende polymer.

14. En metode ifølge krav 1, derudover omfattende personalisering af kortet ved hjælp af en laser, som udsender en laserstråle, hvor laserstrålen skal passere igennem laget med hård belægning, før det interne kernelag rammes, og nævnte bufferlag absorberer energi og varme tildelt til det interne kernelag af laseren.
- 5

DRAWINGS

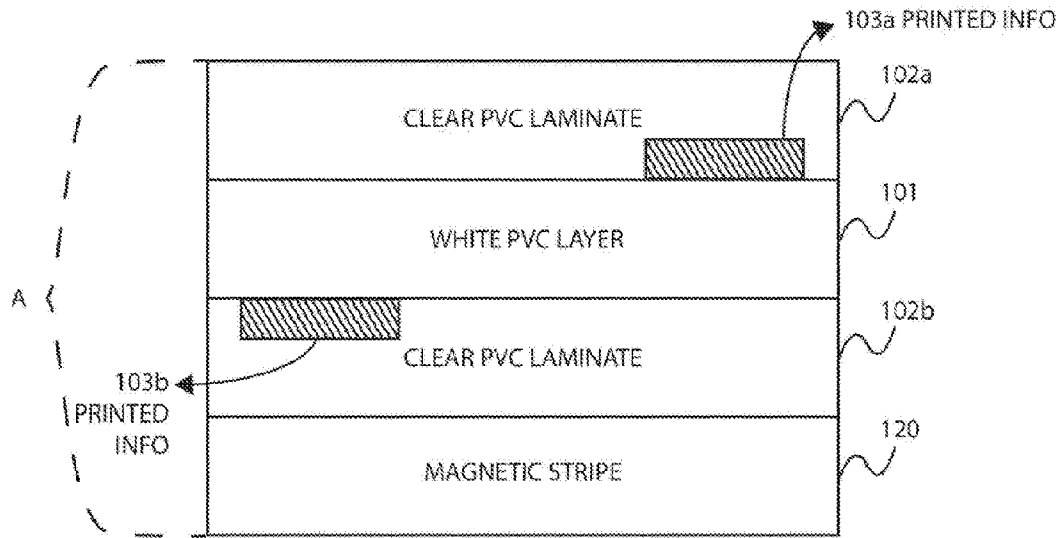


FIG. 1A

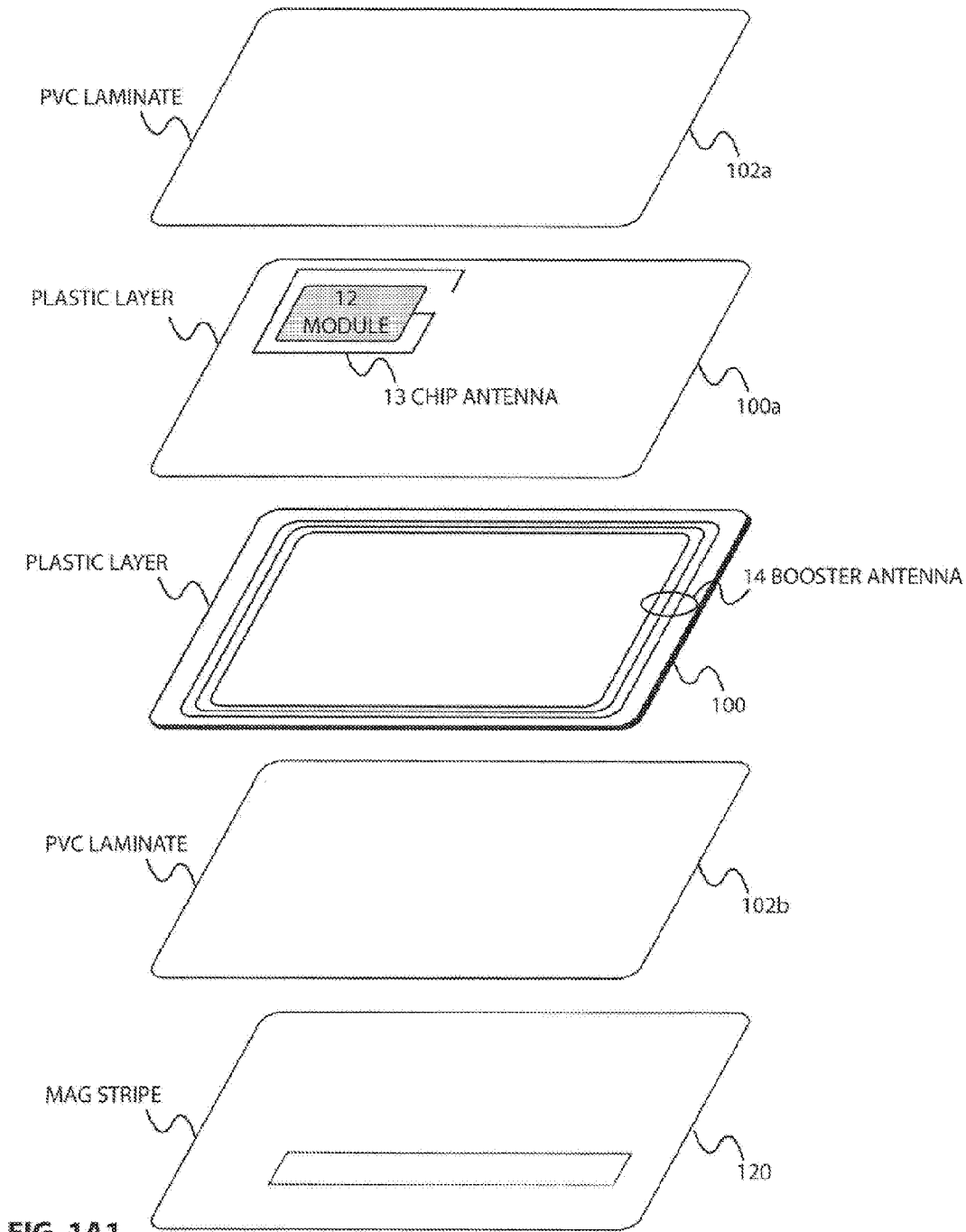


FIG. 1A1

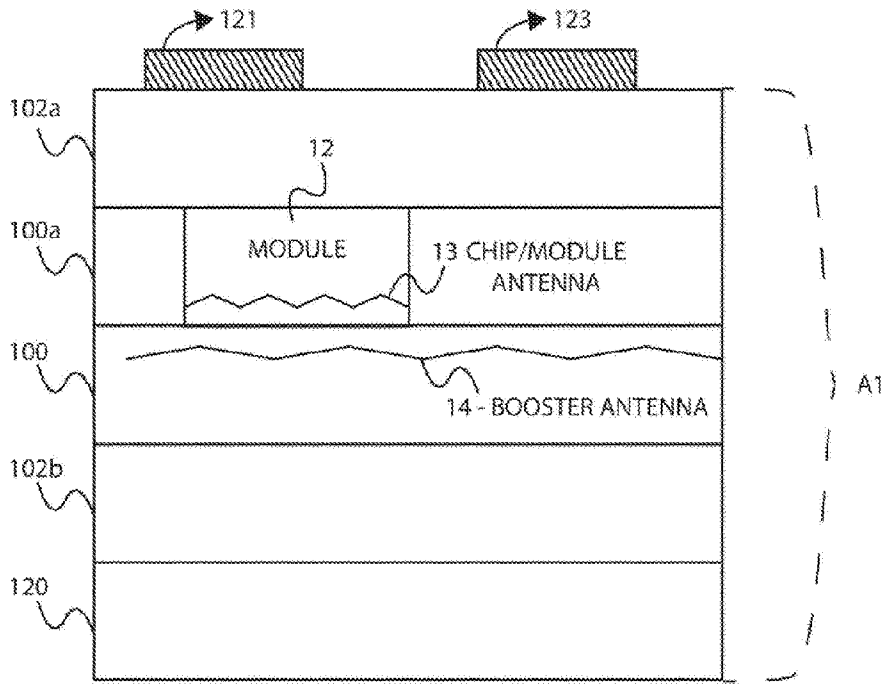


FIG. 1A2

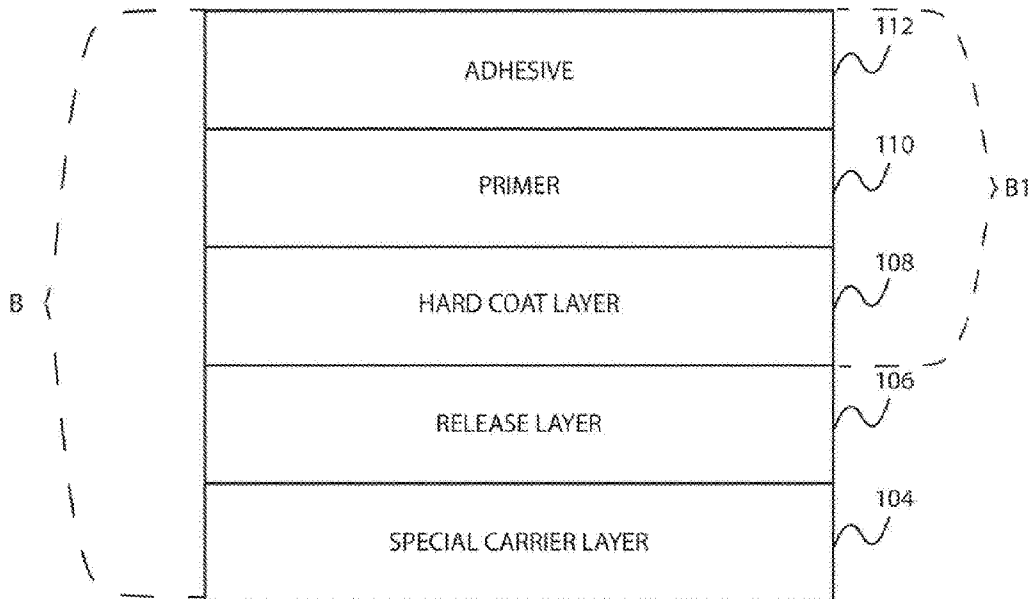


FIG. 1B

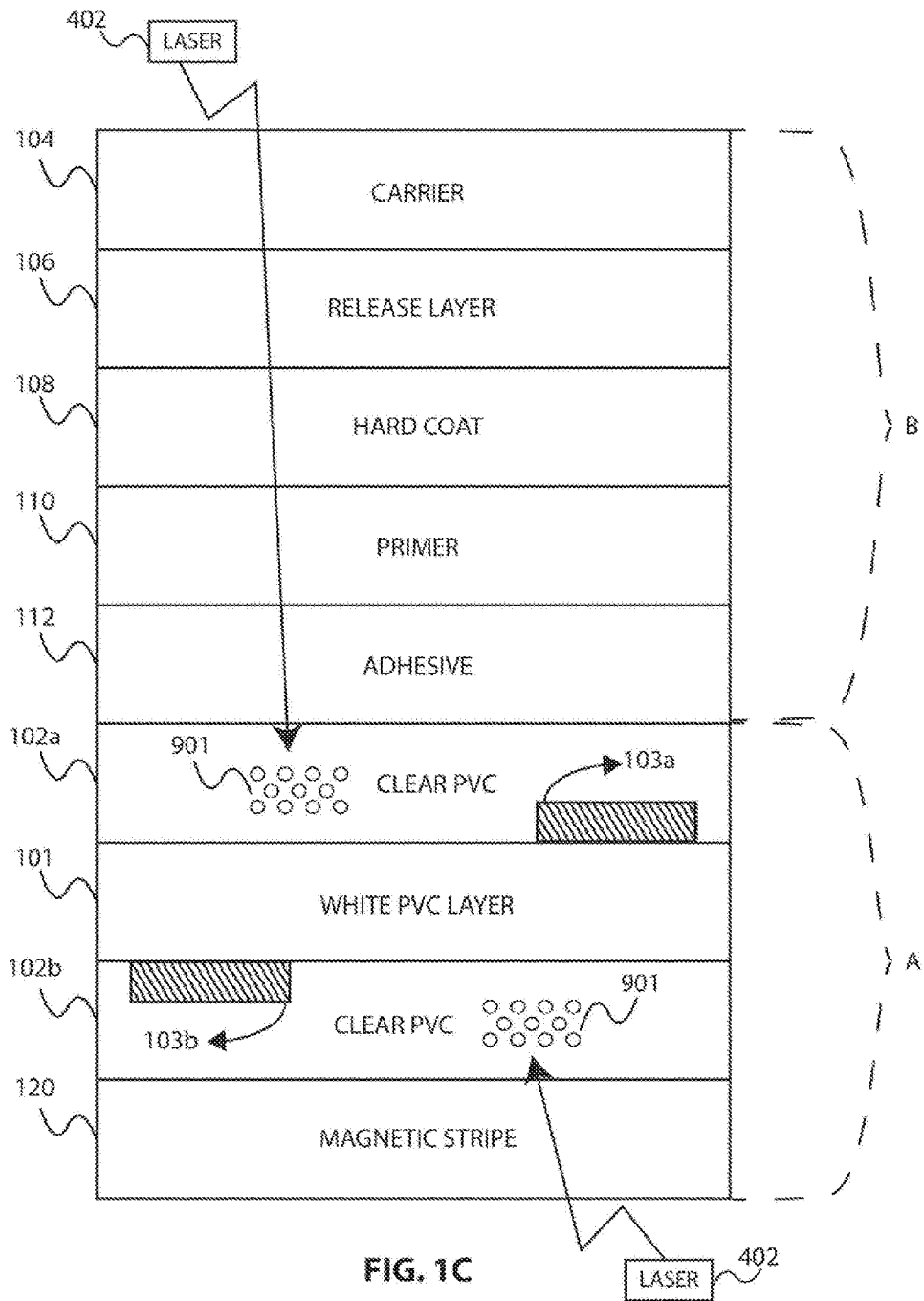


FIG. 1C

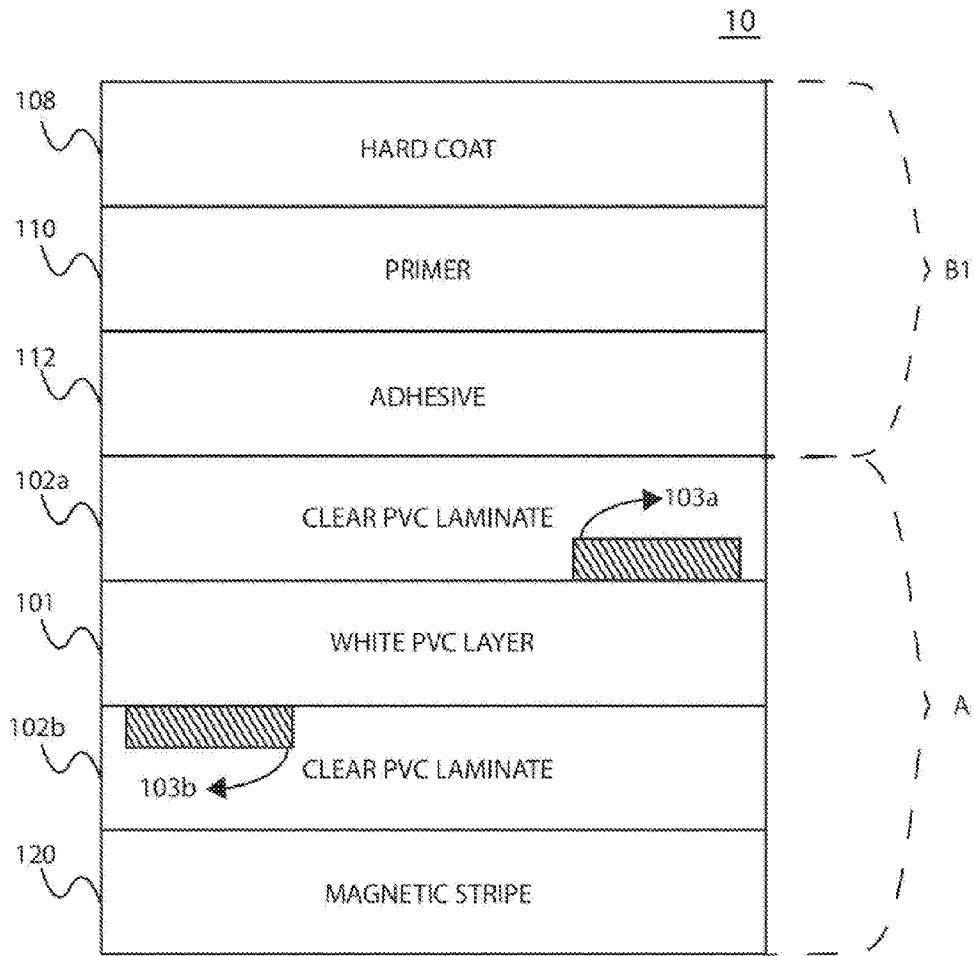


FIG. 1D

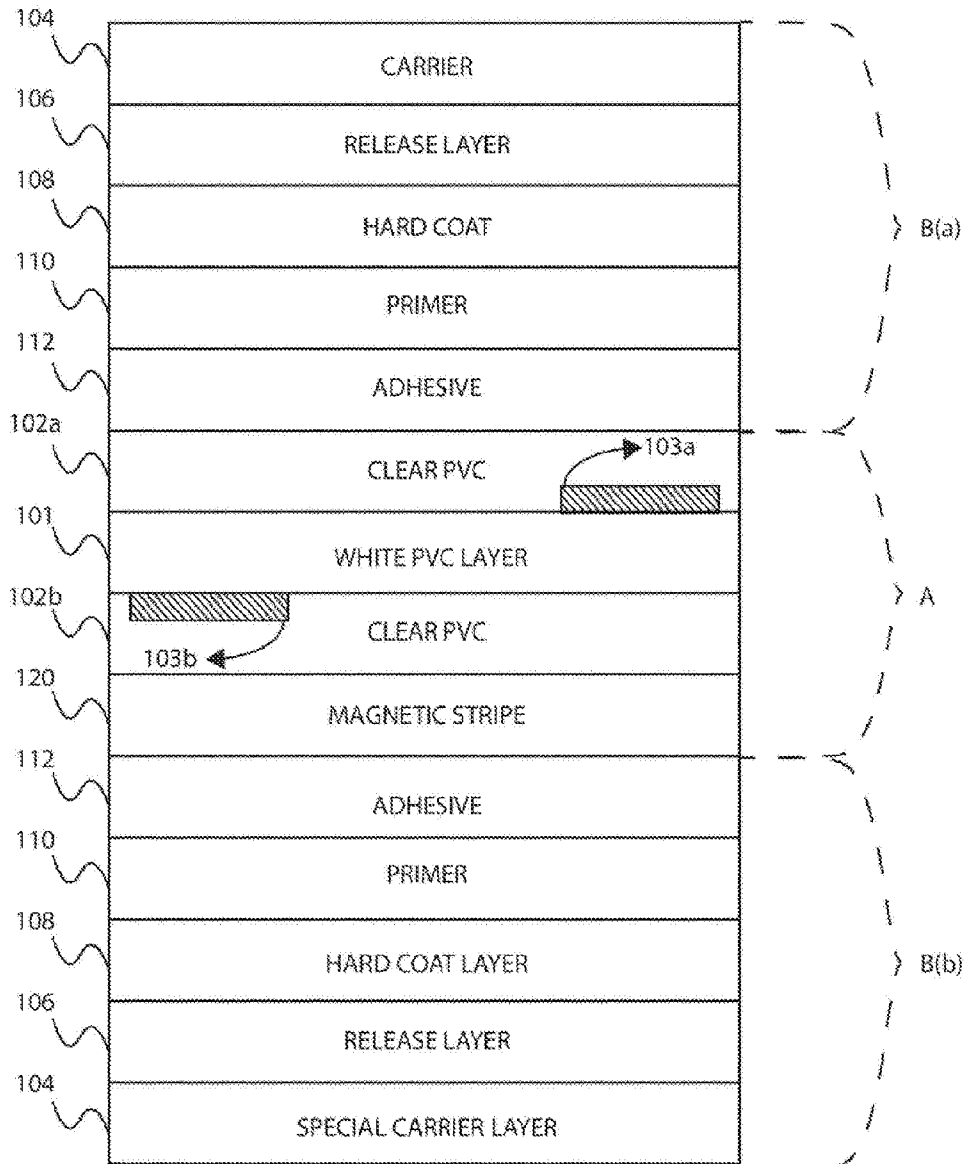


FIG. 2

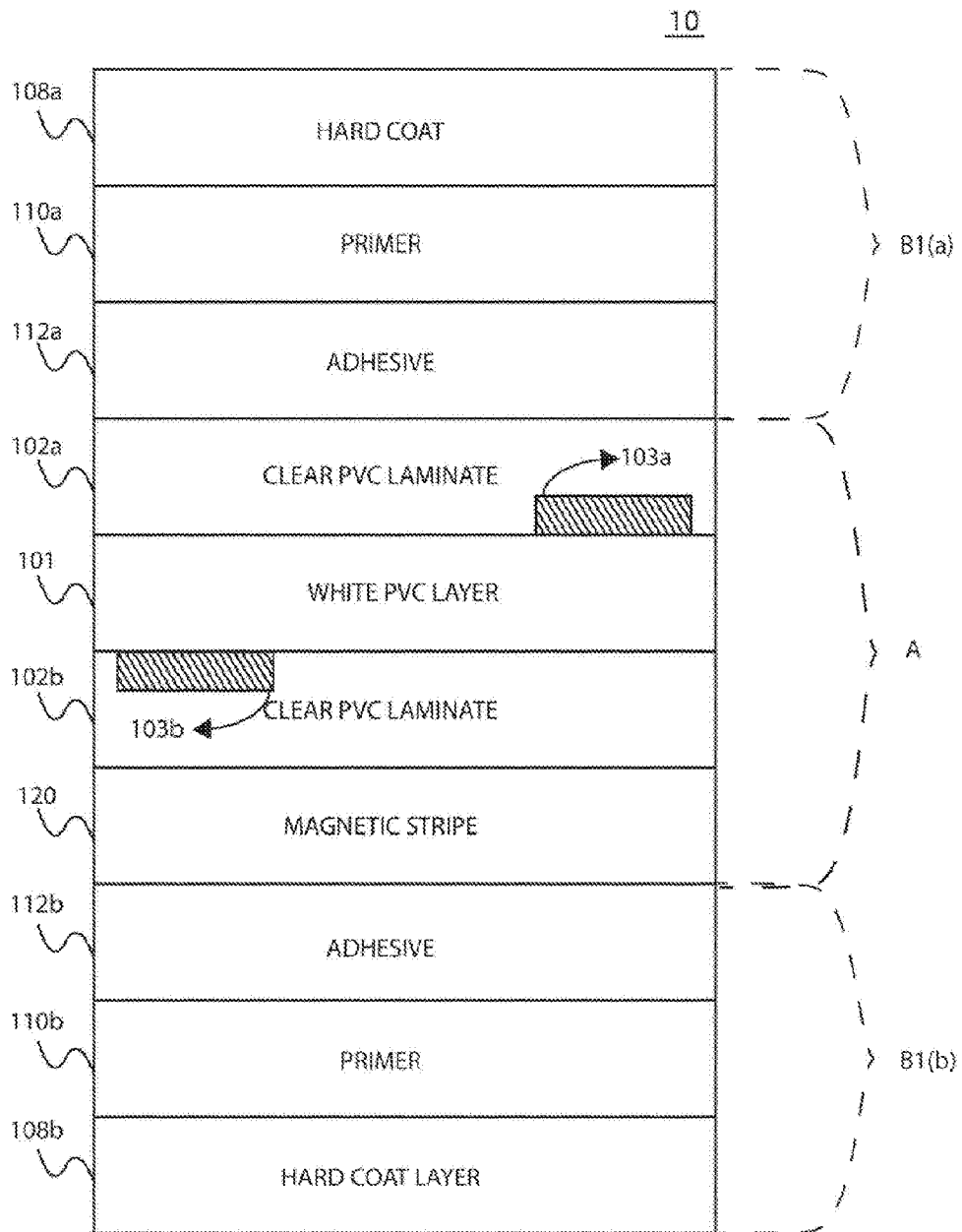
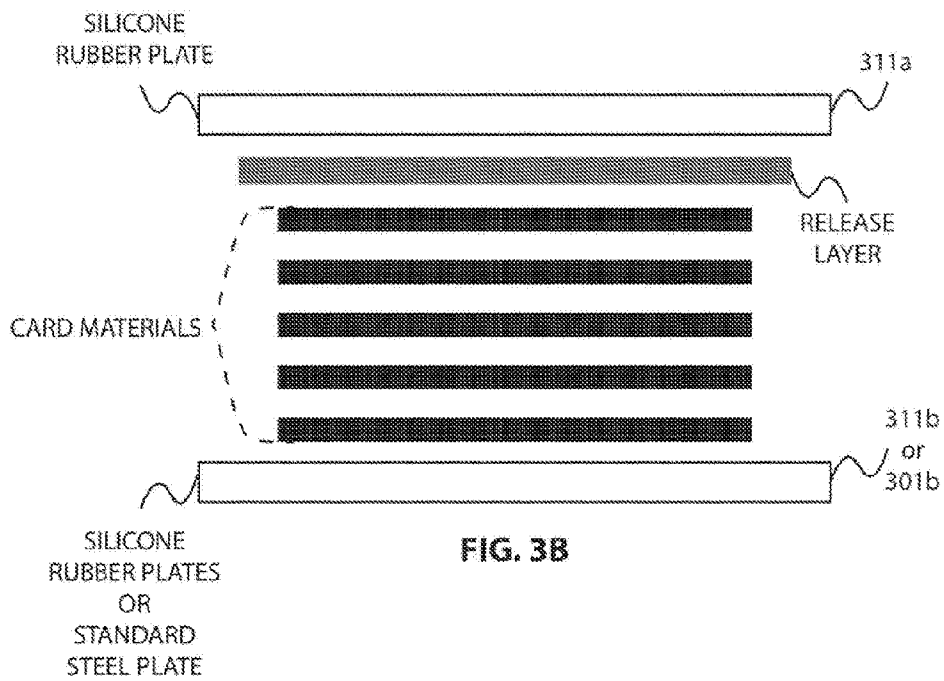
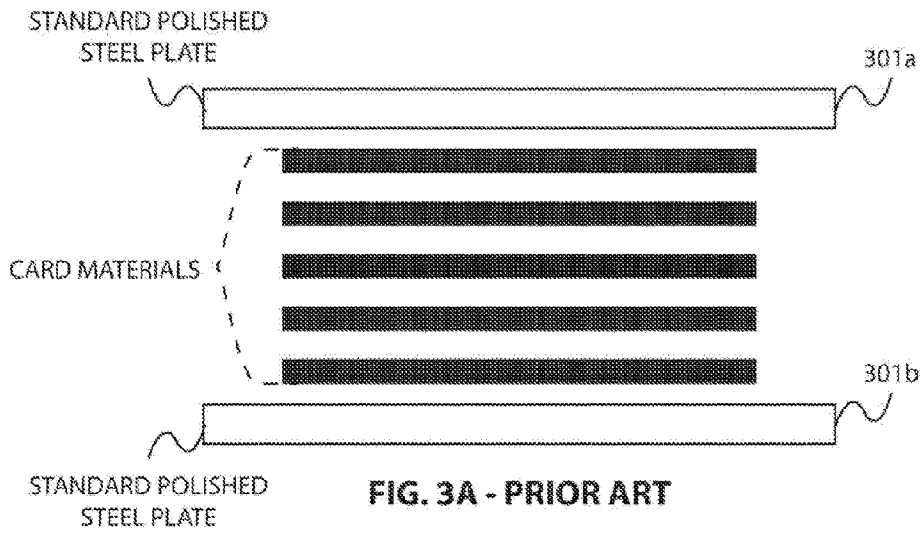


FIG. 2A



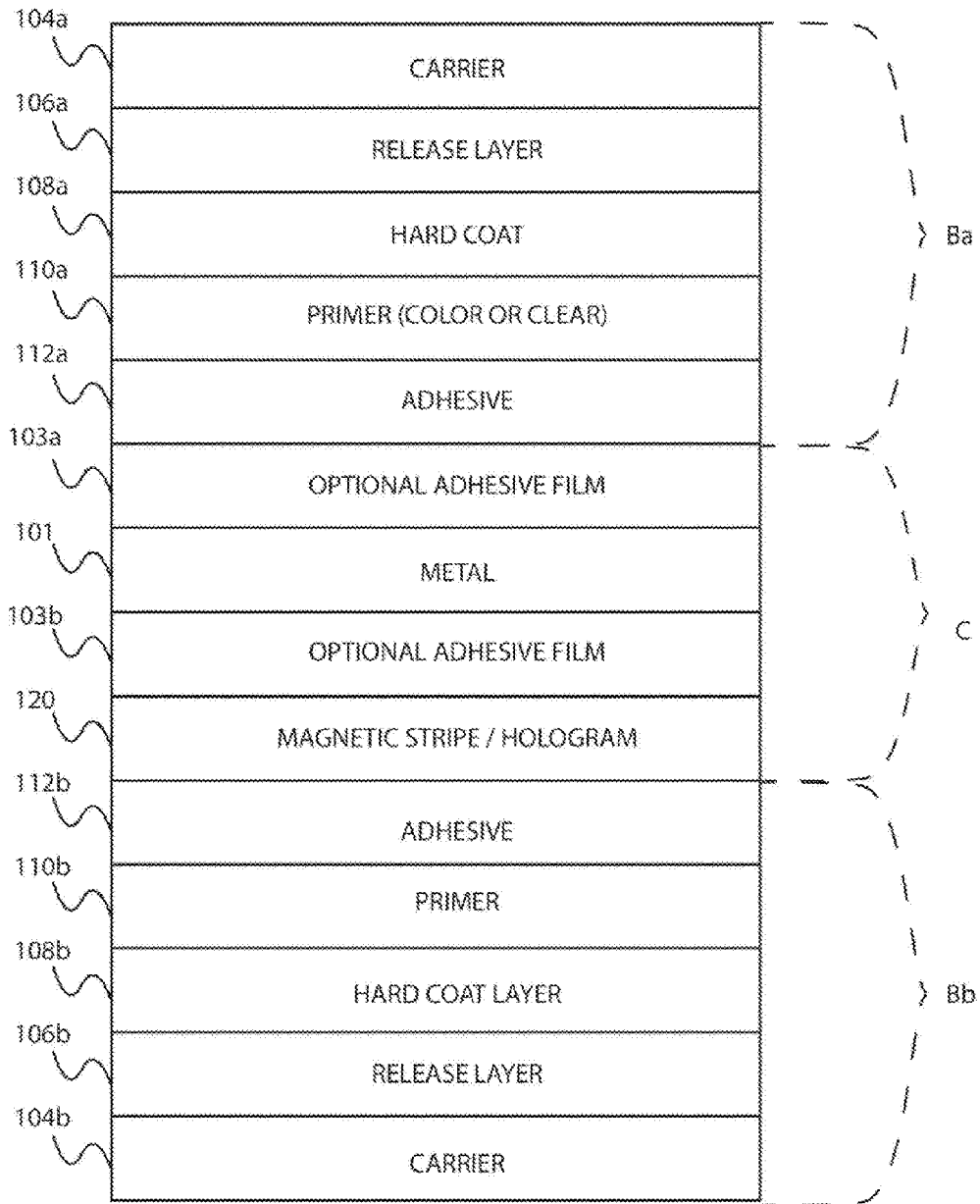


FIG. 4A

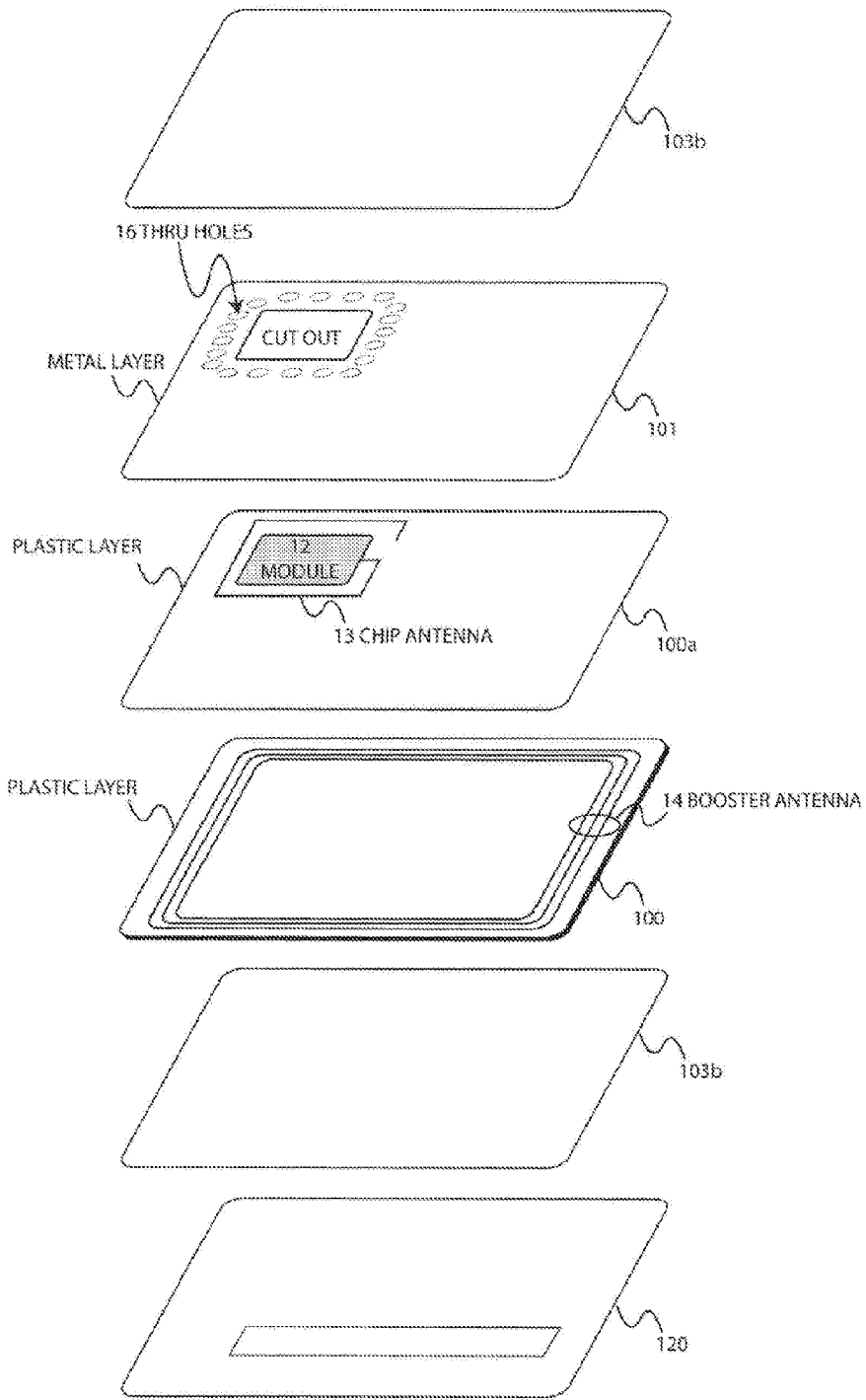


FIG. 4A1

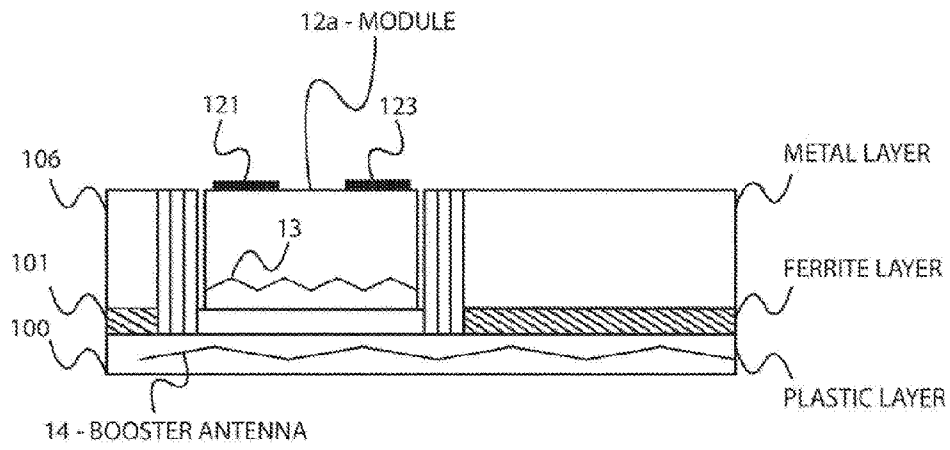


FIG. 4A2

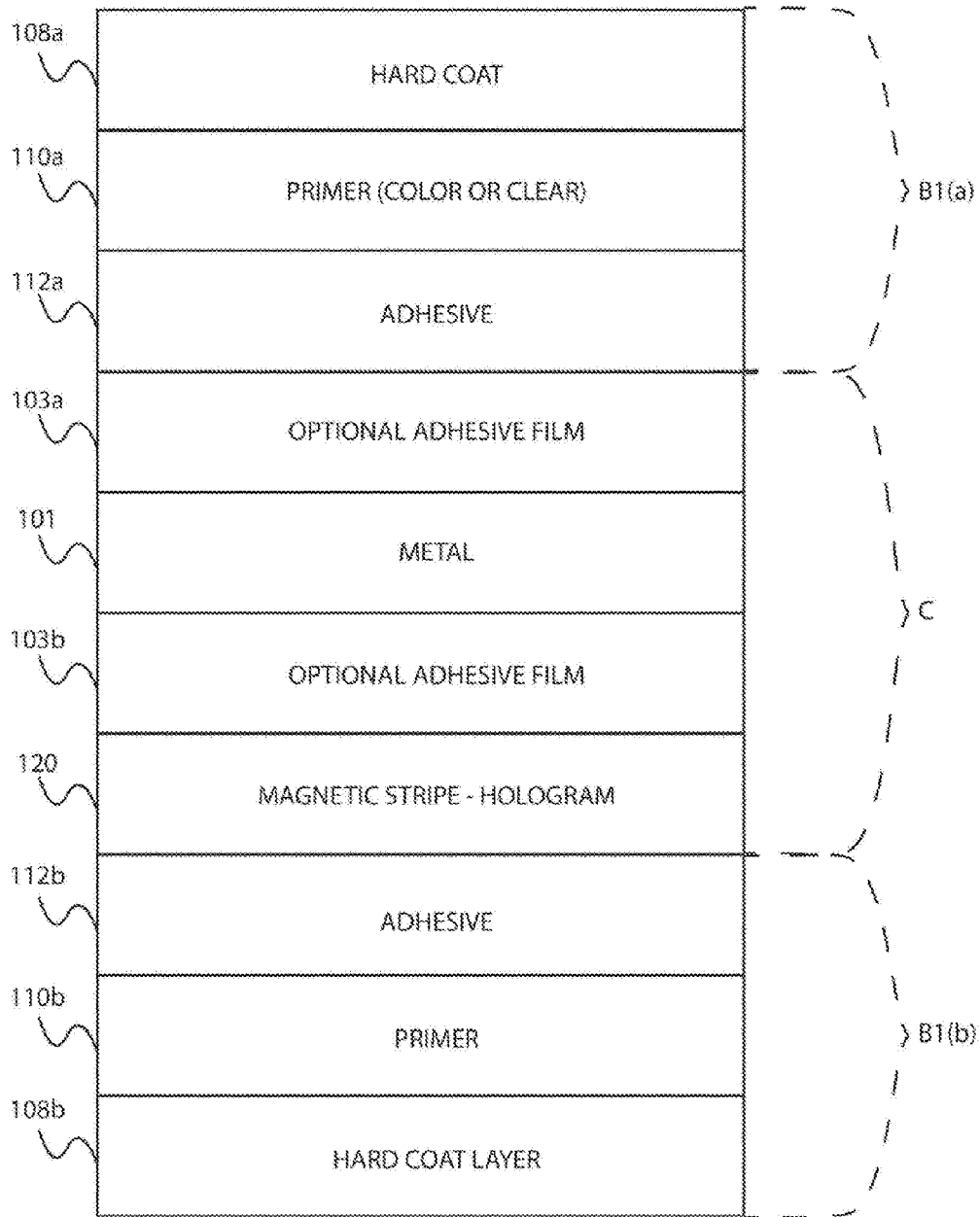


FIG. 4B

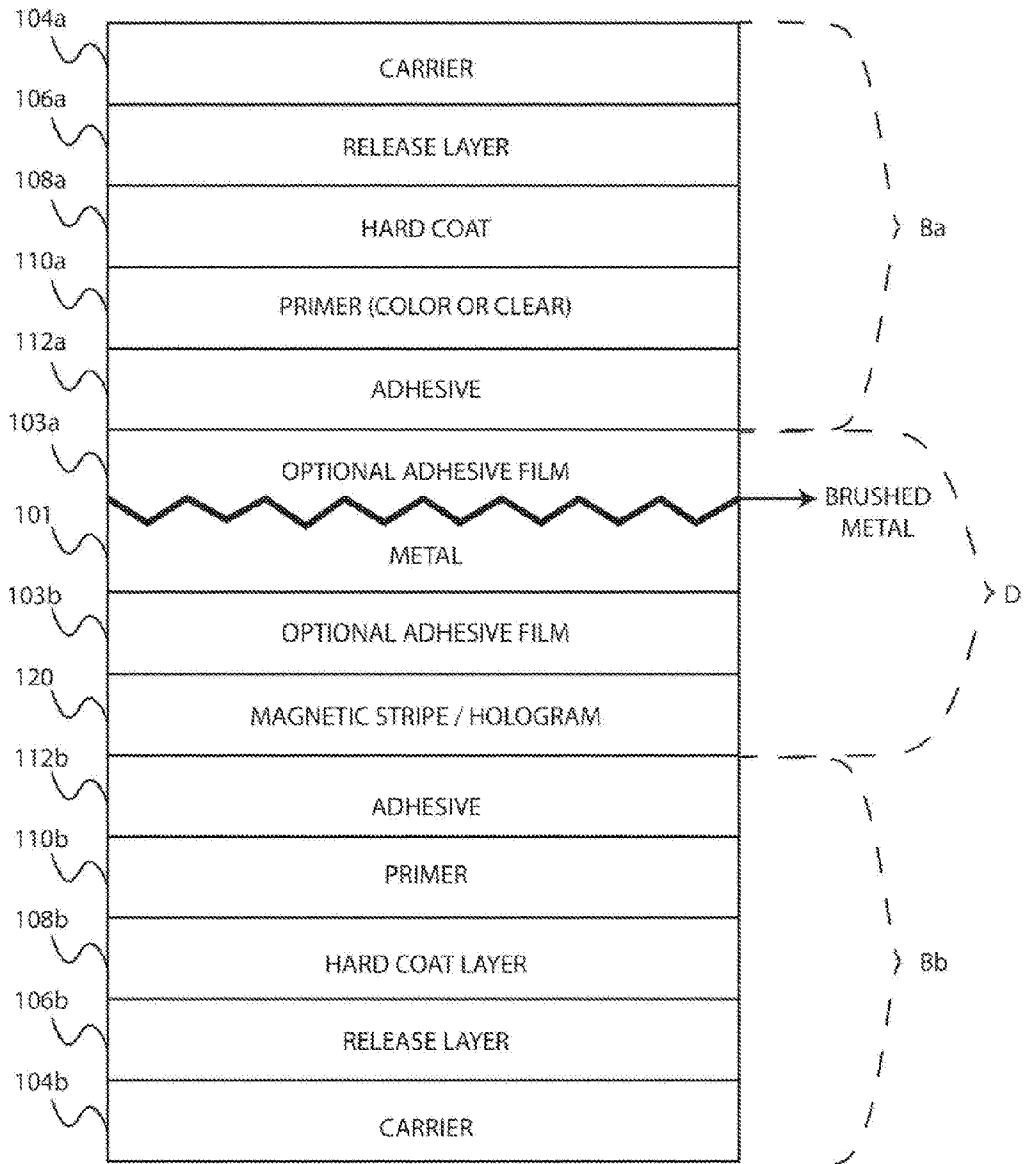


FIG. 5A

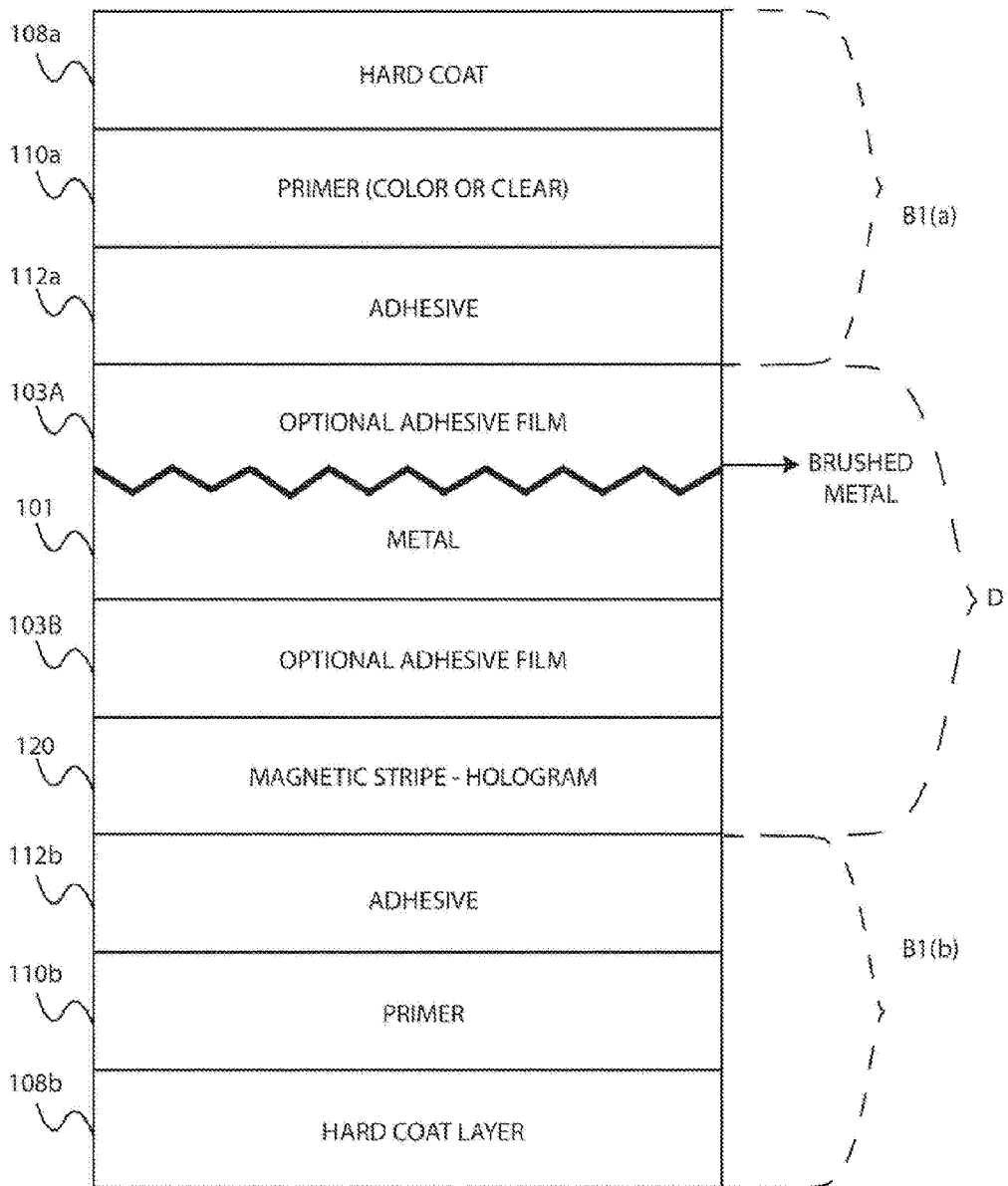


FIG. 5B

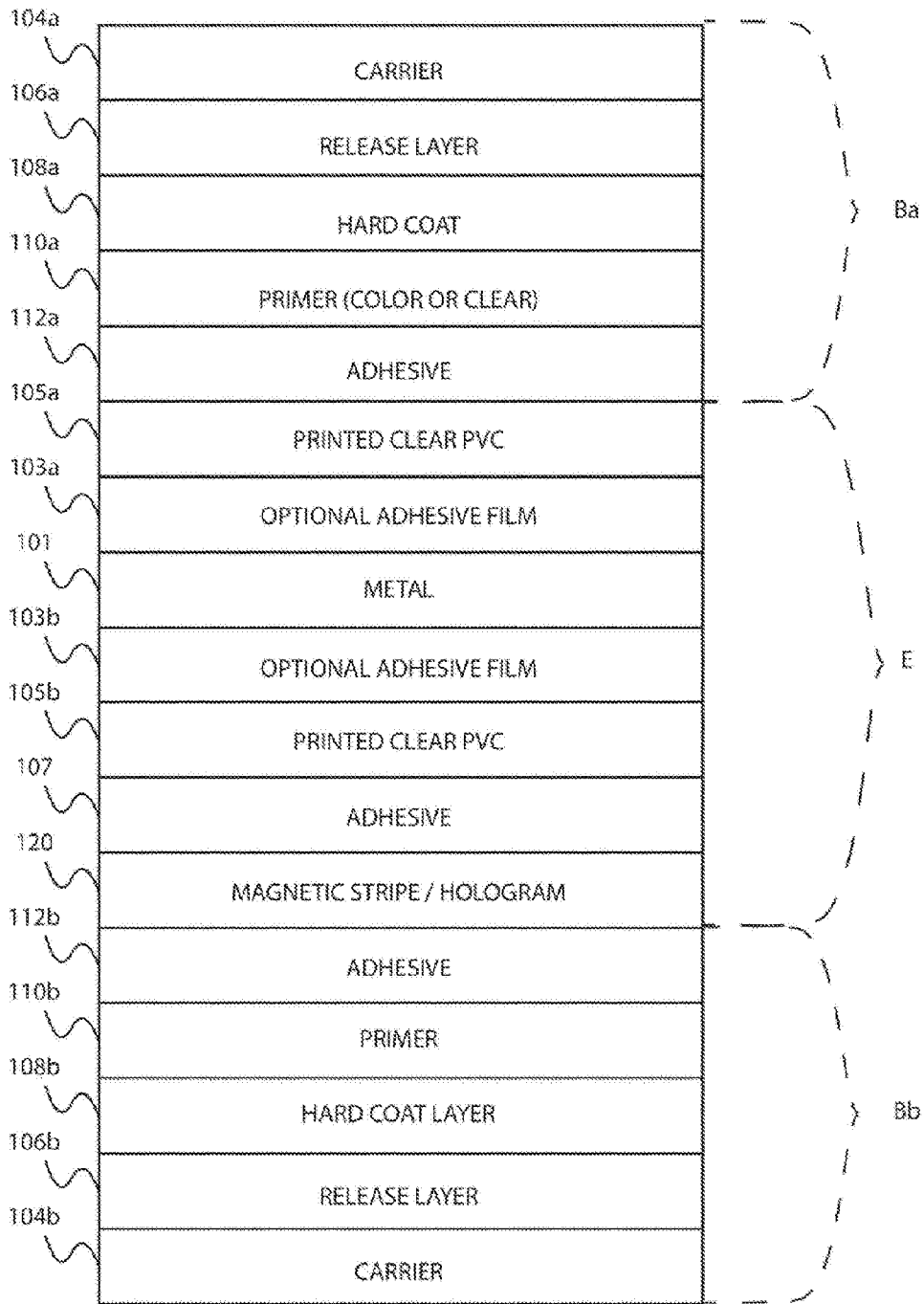


FIG. 6A

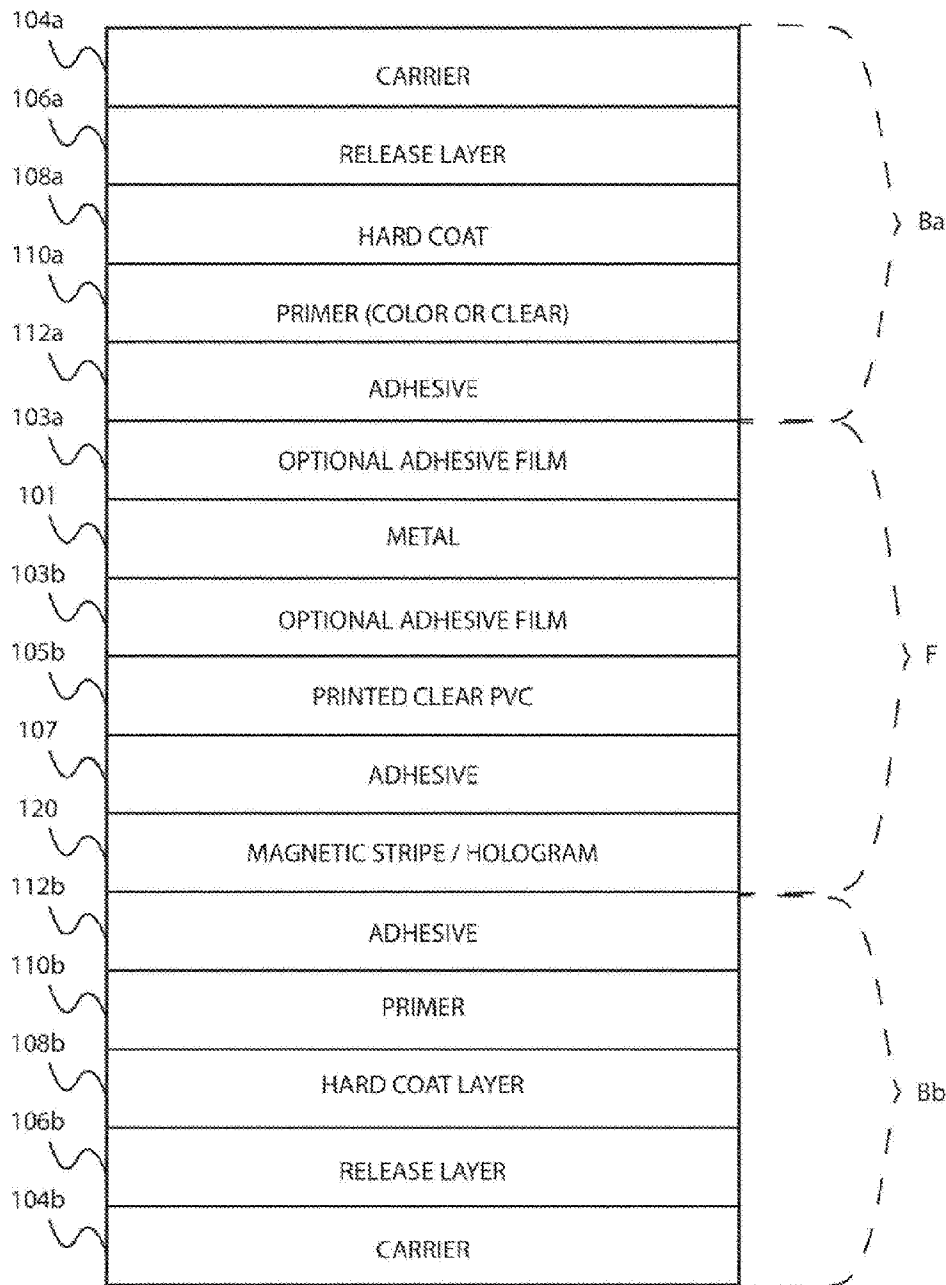


FIG. 6B

PROCESS STEPS

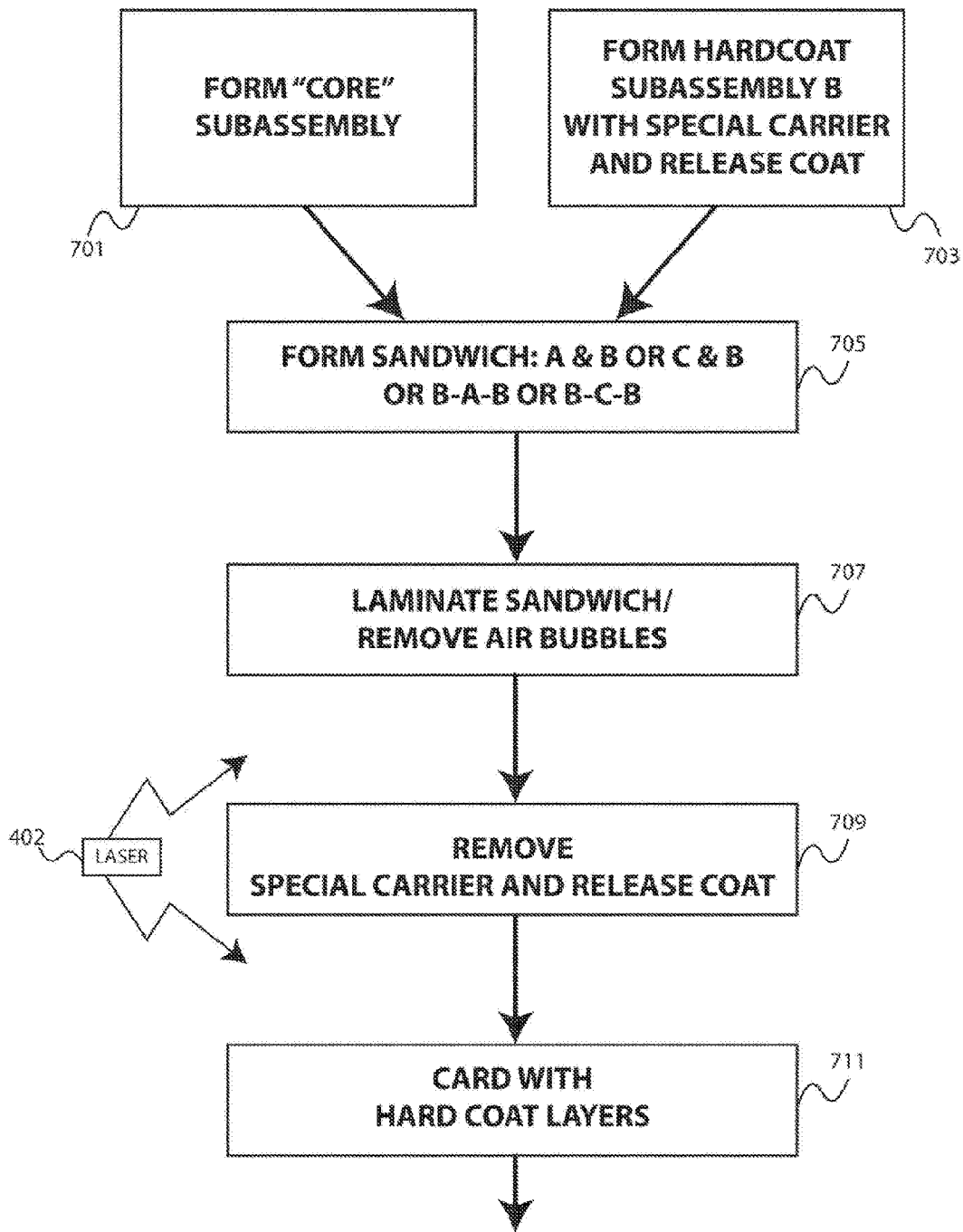


FIG. 7

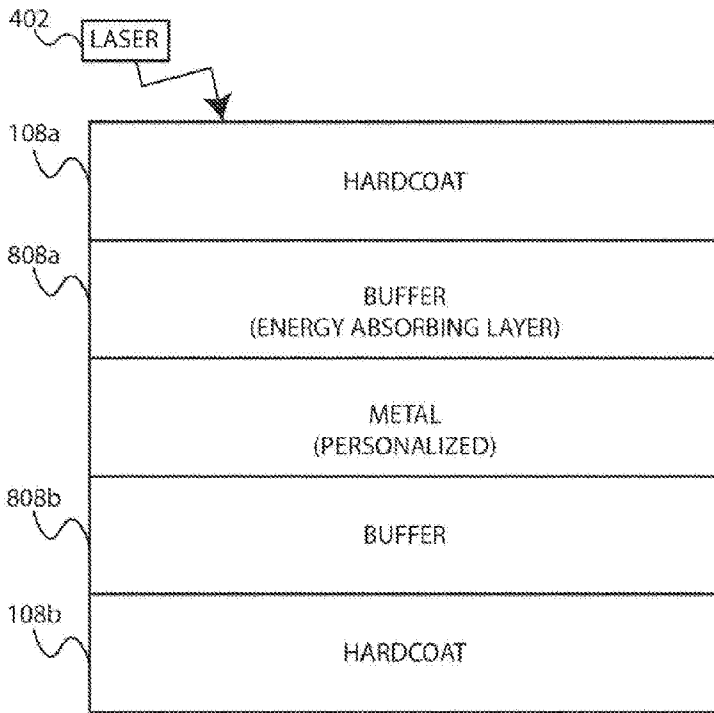


FIG. 8

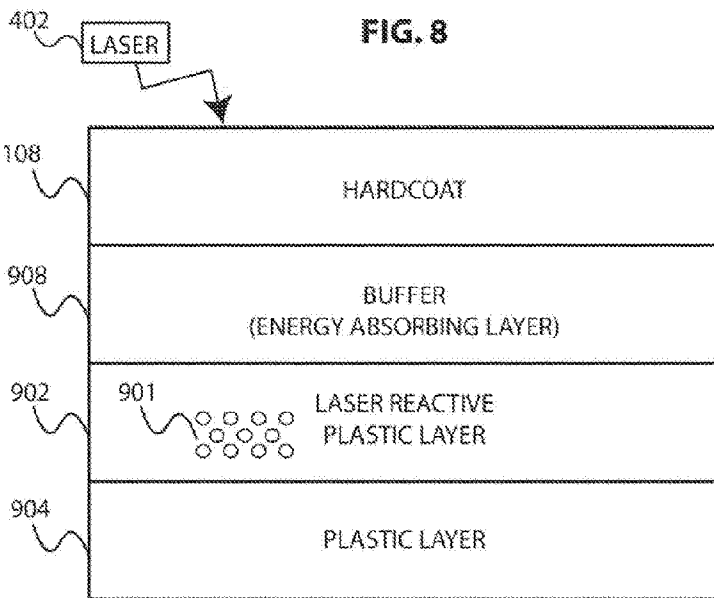


FIG. 9